

Application Data Sheet

Application Information

Application Type::	Regular
Subject Matter::	Utility
Suggested Group Art Unit::	N/A
CD-ROM or CD-R?::	None
Sequence submission?::	None
Computer Readable Form (CRF)?::	No
Title::	A DEVICE AND METHOD FOR SOLDERING CONTACTS ON SEMICONDUCTOR CHIPS
Attorney Docket Number::	20046/0201094-US0
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	Fig. 1
Total Drawing Sheets::	1
Small Entity?::	No
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Germany
Status::	Full Capacity
Given Name::	Robert
Family Name::	Bergmann
City of Residence::	Regensburg
Country of Residence::	Germany
Street of mailing address::	Kirchweg 5
City of mailing address::	Regensburg
Country of mailing address::	Germany

Postal or Zip Code of mailing address:: 93055

Applicant Authority Type:: Inventor
Primary Citizenship Country:: Germany
Status:: Full Capacity
Given Name:: Holger
Family Name:: Hubner
City of Residence:: Baldham
Country of Residence:: Germany
Street of mailing address:: Hamsterweg 10
City of mailing address:: Baldham
Country of mailing address:: Germany
Postal or Zip Code of mailing address:: 85598

Correspondence Information

Correspondence Customer Number:: 07278

Representative Information

Representative Customer Number:: 07278

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Continuation of	PCT/DE02/03506	09/19/02

Foreign Priority Information

Country::	Application number::	FilingDate::	Priority Claimed::
Germany	101 47 789.9	09/27/01	Yes

Assignee Information

Assignee name:: Infineon Technologies AG
Street of mailing address:: St.-Martin-Strasse 53

City of mailing address:: Munich
Country of mailing address:: Germany
Postal or Zip Code of mailing address:: 81669